<b>PCN Number:</b> 20161230002				PCN Da	ite:	Feb. 14, 2017			
Title: Datasheet for ONET1131EC									
Customer Contact: PCN Manager			D			pt:	Qua	lity Services	
Change Type:									
Assembly Site			Design			Wafer B		Bump Site	
Assembly Process		$\square$	Data Sheet			Wafer	Bump Material		
Assembly Materials			Part number change	e			Bump Process		
Mechanical Specification			Test Site				Fab Site		
Packing/Shipping/Labeling			Test Process				er Fab Materials		
			otification Details				r Fab Process		
Description of Change:									
Texas Instruments Incorporated is announcing an information only notification.									
The product datasheet(s) is being updated as summarized below. The following change history provides further details.									
<b>INSTRUMENTS</b>			SLLSEQ6		BER 2	016-REVISE			
Changes from Original (September 2016) to Revision A Page   • Deleted sentence "however, this function" from the second paragraph of the CDR section									
The datasheet number will be changing.									
Device Family ONET1131EC			Change From:					ige To:	
UNLITIBLEC			SLLSEQ6			SLLSEQ6A			
These changes may be reviewed at the datasheet links provided. <u>http://www.ti.com/product/ONET1131EC</u> <b>Reason for Change:</b>									
To more accurately reflect device characteristics.									
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.									
Changes to product identification resulting from this PCN:									
None.									
Product Affected:									
ONET1131ECRSMR ONET1131ECRSMT									
	•								

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com